

HVC202B

Variable Capacitance Diode for UHF/VHF tuner

REJ03G0096-0200Z

(Previous: ADE-208-406A)

Rev.2.00

Sep.23.2003

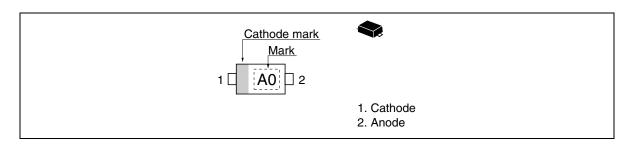
Features

- Low matching error. ($\Delta C/C = 1.80\%$ max)
- High capacitance ratio. (n = 6.30 min)
- Low series resistance. (rs = $0.57 \Omega \text{ max}$)
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC202B	A0	UFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Peak reverse voltage	V _{RM} *1	35	V
Reverse voltage	V _R	32	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 1. $R_L = 10 \text{ k}\Omega$

Electrical Characteristics

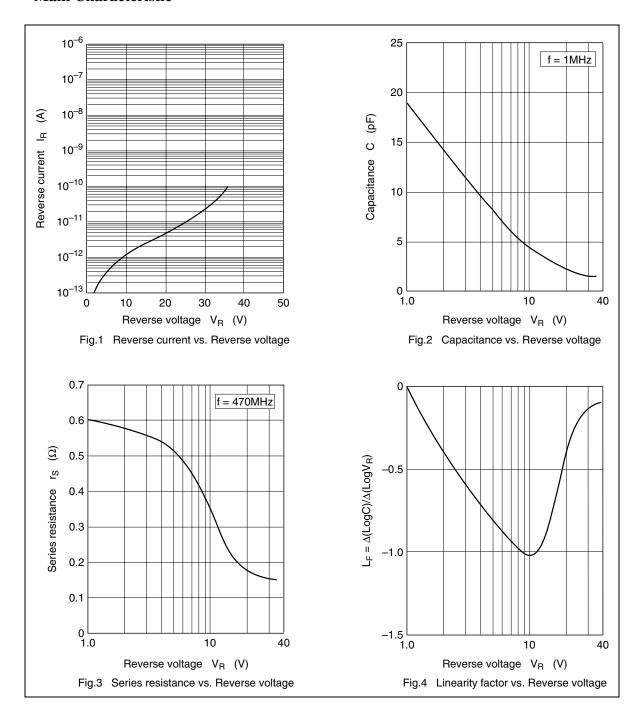
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 30 V
	I _{R2}	_	_	100		$V_{R} = 30 \text{ V}, \text{ Ta} = 60^{\circ}\text{C}$
Capacitance	C ₂	14.15	_	15.75	pF	V _R = 2 V, f = 1 MHz
	C ₂₅	2.06	_	2.35	_	V _R = 25 V, f = 1 MHz
Capacitance ratio	n	6.30	_	_	_	C ₂ /C ₂₅
Series resistance	r _s	_	_	0.57	Ω	V _R = 5 V, f = 470 MHz
Matching error	ΔC/C *1	_	_	1.80	%	V _R = 2 to 25 V, f = 1 MHz

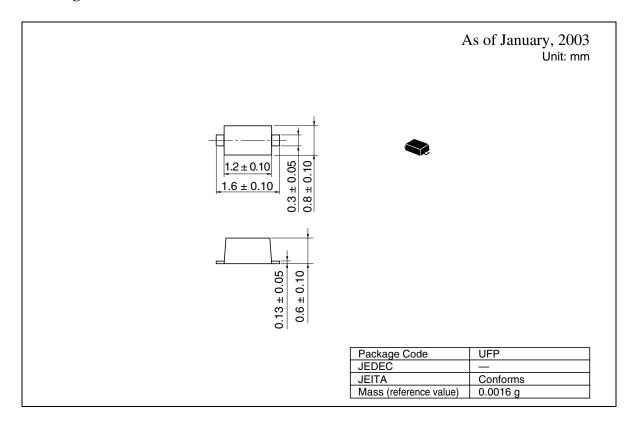
Note: 1. C.C system (Continuous Connected taping system) enable to make any 10 pcs of $\Delta C/C$ continuous in a reel , expect extention to another group. Calculate Matching Error,

$$\Delta C/C = \frac{(Cmax - Cmin)}{Cmin} \times 100 \text{ (\%)}$$

Main Characteristic



Package Dimensions



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